ASSOCIATION CONNECTING ELECTRONICS INDUSTRIESS International and Pa	IPC. Bannockl	ourn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati the declaration e	on of the su	bstances v s all lower	vithin the manufactu level materials for v	rer listed which the 1	item. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
				Form Type Distribute	*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					tion			
upplier Information														
Company name*	Company un	Company unique ID			Unique ID Authority				Respon	Response Date*				
onsemi										2025-09	2025-09-10			
Contact Name Title - Contac			ntact			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Produc			roduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title -			itle - Representative			Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards Product			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	r Mfr Item Name			Effective Date	Version	Version Manufacturing Site			Weight*	UOM	Unit Type	
	SZ1SMI	SZ1SMB5913BT3G ZEN		ZEN SMB REG 3W 3.3V SPCL		2025-09-10		V	VN5		114.91	mg	Each	
Ianufacturing Proccess Informa	ation						-	·						
Terminal Plating / Grid Array M	Iaterial 7	Ferminal Base	Alloy	J-STD-020 MSL Rating		Peak Proce	Peak Process Body Temperat		ure Max Time at Peak Ter		ture Num	ber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU		CU Alloy	1			260 C		С	30 seco		seconds 3			
omments														
vel 1 - maximum time at peak temperat	ture during so	ldering is 10-3	0 seconds											
or more information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	16.81	mg	Supplier	Zinc (Zn)	7440-66-6		0.0202	mg
			Supplier	Iron (Fe)	7439-89-6		0.395	mg
			Supplier	Copper (Cu)	7440-50-8		16.3897	mg
			Supplier	Phosphorus (P)	7723-14-0		0.005	mg
Die	0.7	mg	Supplier	Silicon (Si)	7440-21-3		0.7	mg
Die Attach Solder	0.52	mg	Supplier	Silver (Ag)	7440-22-4		0.013	mg
			А	Lead (Pb)	7439-92-1	7a	0.481	mg
			Supplier	Tin (Sn)	7440-31-5		0.026	mg
Lead Frame	46.99	mg	Supplier	Zinc (Zn)	7440-66-6		0.0564	mg
			Supplier	Iron (Fe)	7439-89-6		1.1043	mg
			Supplier	Copper (Cu)	7440-50-8		45.8153	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0141	mg
Mold Compound-Black	48.07	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.807	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2403	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		6.9701	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		31.2455	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		4.807	mg
Plating	1.82	mg	Supplier	Tin (Sn)	7440-31-5		1.82	mg